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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT OPERATIONS**

Art Unit: (Examiner) RECEIVED
 Applicant(s): Andreas PLETTNER and Karl HABERGER JUN 05 2001
 Serial No: 09/787,638 Technology Center 2600
 Filed: March 20, 2001
 Title: METHOD FOR PRODUCING A MICROTRANSPOUNDER

Charlotte, North Carolina
April 2, 2001

Honorable Commissioner of Patents and Trademarks
Washington, D. C. 20231

Dear Sir:

CERTIFICATE OF MAILING

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patent and Trademarks, Washington, D.C. 20231, on: April 2, 2001

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April 2, 2001
 Date

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INFORMATION DISCLOSURE STATEMENT

REMARKS

The attached PTO Form SB/08A is incorporated as part of the Information Disclosure Statement. A copy of each cited document was submitted with the application as filed. Applicants submit herewith patents, publications, or other information of which they are aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR 1.56.

While this Information Disclosure Statement may be "material" pursuant to 37 CFR 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is "prior art" for this invention unless specifically designated as such.

In accordance with 37 CFR 1.97(b), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 CFR 1.56(a) exists.

The following prior art documents were cited during the examination proceedings before the European Patent Office as International Preliminary Examination Authority.

Documents cited in the German Examination Proceedings

1. **DE 433 79 21 A1** relates to a contactless chip card having a housed chip arranged substantially on center in a chip card laminate. The chip housing 1 has a housing foil 4 protruding from the chip housing all-around. Leads 3 and pads 5 are arranged on the housing foil 4 and connected to pads 8, 10 of an antenna coil 7 provided on one of the laminate sheets adjacent to the housing foil. Thus, according to DE 433 79 21 A1, the chip is arranged in a chip housing such that encapsulating of the chip is not necessary, as it is provided according to the present invention by means of joining edge areas of a flexible support foil to neighboring areas of the support substrate, so as to encapsulate the chip.
2. **DE 195 49 431 A1** relates to a chip support foil HCT on which a chip C is arranged. The chip C is coated with a protective drop CC formed of strongly insulating plastic. The chip is arranged on one side of the chip support foil and conductive lines L1, L2 are provided on the other side thereof. The conductive lines are used to connect pads on the chip C to terminals of an antenna metallization A provided on an antenna support foil HM. Since the chip is coated with a protected plastic drop CC, encapsulating same using a flexible support foil is not necessary according to DE 195 49 431 A1.

3. **DE 196 09 149 A1** relates to a chip card comprising a chip carrier element 11 inserted into a recess 10 of a coating foil 3. A chip is arranged on the chip carrier element and coated with a protective encapsulating body 26.

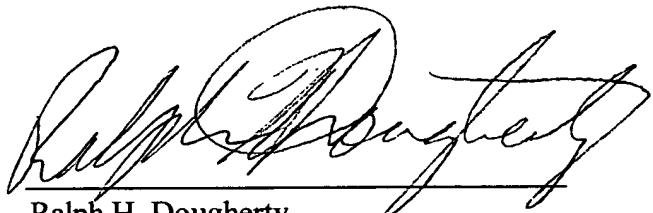
4. **EP 0 595 549 A2** relates to transponder tags 20 built on a thin flexible substrate. According to this document, a transponder circuit chip 26 is adhered to the thin flexible substrate using structural adhesive 86 such that contact pads 72, 74 on the bottom side of the chip are connected to antenna pads 34, 36 on the thin flexible substrate 30.

Documents cited in the International Examination Proceedings

1. **EP 0 723 244 A** relates to a data carrier comprising cover sheets 7 and 16 and intermediate sheets 8, 13 and 15 comprising recesses for respective elements, an antenna coil 2, a support substrate 5 and an integrated circuit 4, for example. Thus, according to this document, this respective elements are fully housed by the intermediate sheets and the cover sheets.

2. **EP 0 704 816 A2** relates to an IF transponder having an antenna metallization 6 applied to a carrier substrate 2. Also applied to the carrier substrate is a chip, wherein a lead line 16 is provided to connect a pad on the chip to an outer terminal of the antenna metallization. In order to separate the lead line 16 from the antenna coil, a dielectric layer 18 is arranged therebetween.

Respectfully submitted,



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Attorney's Docket 3132

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SUPPLEMENT TO FORM PTO/SB/08A

**INFORMATION DISCLOSURE CITATION EXPLAINING
THE RELEVANCE OF EACH LISTED ITEM**

Documents cited in the German Examination Proceedings

1. DE 433 79 21 A1
2. DE 195 49 431 A1
3. DE 196 09 149 A1
4. EP 0 595 549 A2

Documents cited in the International Examination Proceedings

1. EP 0 723 244 A
2. EP 0 704 816 A2